## **APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

Title of Invention

INTEGRATED CIRCUIT PACKAGE AND PRINTED CIRCUIT BOARD

**ARRANGEMENT** 

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Correspondence address:

**Customer Number:** 20915

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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.	
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